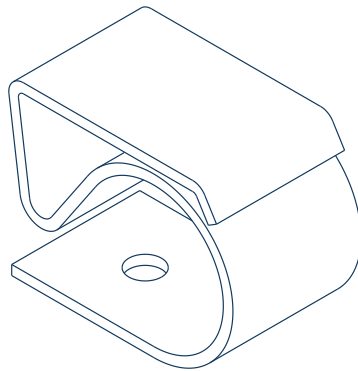




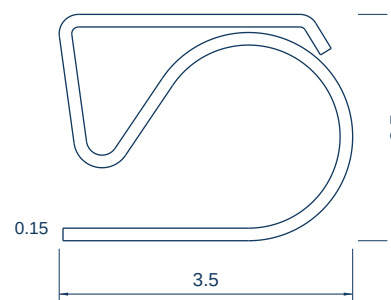
Type D-01 BD01-20035027

SMD EMI Spring Contact | Beryllium Copper | Units: mm

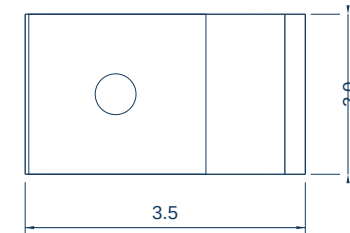
Isometric



Front view (mm)



Top view (mm)



MECHANICAL

VALUE

Thickness	0.15 mm
Width	2.0 mm +/- 0.2
Length	3.5 mm +/- 0.2
Height	2.7 mm +/- 0.2
Form	D-clip: land, 236 deg loop, web, V, leg, top arm, kicked tip
Base land	2.21 mm flat SMD land
D loop	R1.167 CL (R1.242 outer / R1.092 inner), 236 deg
Diagonal web	1.00 mm at 34 deg to the vertical
V bend / side leg	R0.262 CL, 138 deg / 1.30 mm at 8 deg
Top corner / arm	R0.157 CL, 98 deg / 2.64 mm flat top arm
Tip kink / tip	R0.148 CL, 59 deg / 0.35 mm free tip
Land hole	dia 0.51 at 1.13 from the land end, on the centreline (est.)
Developed length	13.35 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	3.975 mm ³ 33.2 mg (BeCu)
File format	STEP AP214

PRODUCT DATA

VALUE

Mfr P/N	BD01-20035027G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 3.5x2.0x2.7mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Application	Board-to-board connection, tape-and-reel for automated SMT lines
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-d-01.html